Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**Top Material: Al**

**Backside Material: Ti Ni Ag**

**Bond Pad Size: .004” X .004”**

**Backside Potential: Cathode**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .138” X .217” DATE: 4/25/22**

**MFG: IXYS THICKNESS .015” P/N: DWEP23-06**

**DG 10.1.2**

#### Rev B, 7/19/02